Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays
Marketing Name / Model [List multiple models if applicable.]
HP Pavilion 23tm Touch Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		12
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		4
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

PSG instructions for this template are available at EL-MF877-01

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screw driver of "+" type	200mm
Description #2 Hexagonal nut screw driver for DVI and D-SUB connector	200mm
Description #3	
Description #4	
Description #5	

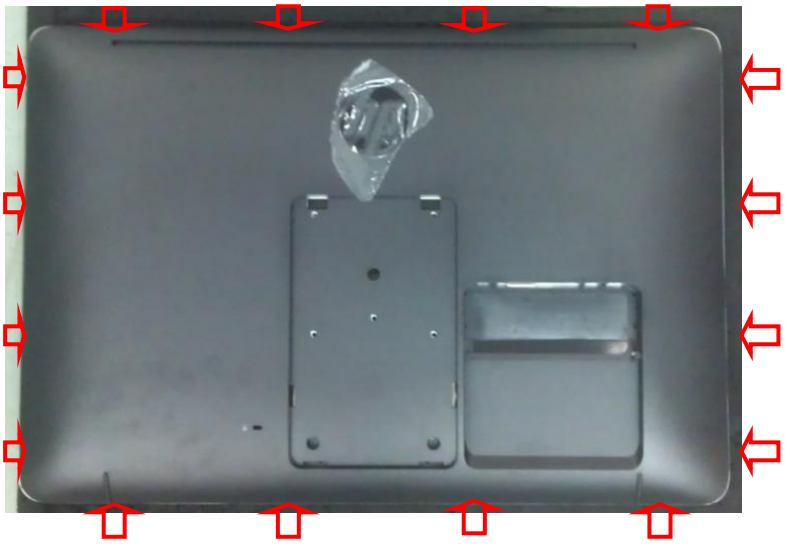
3.0 Product Disassembly Process

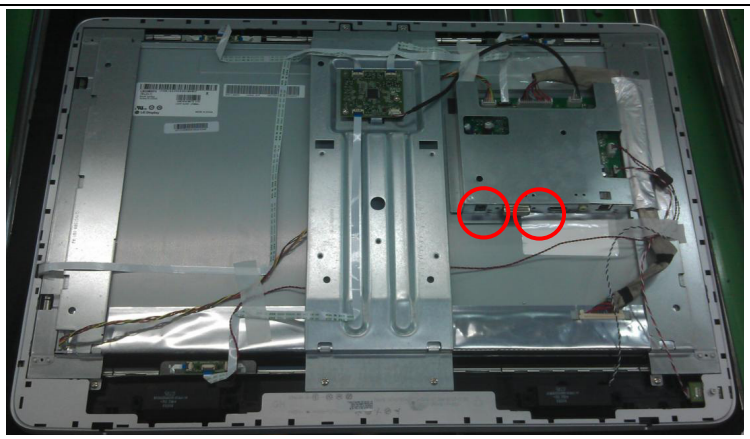
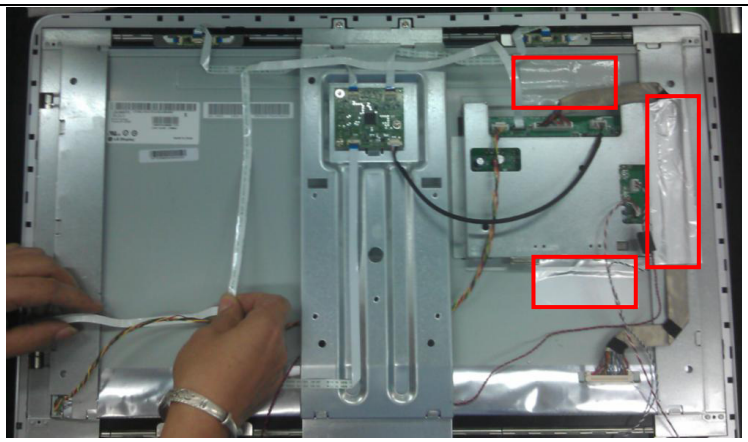
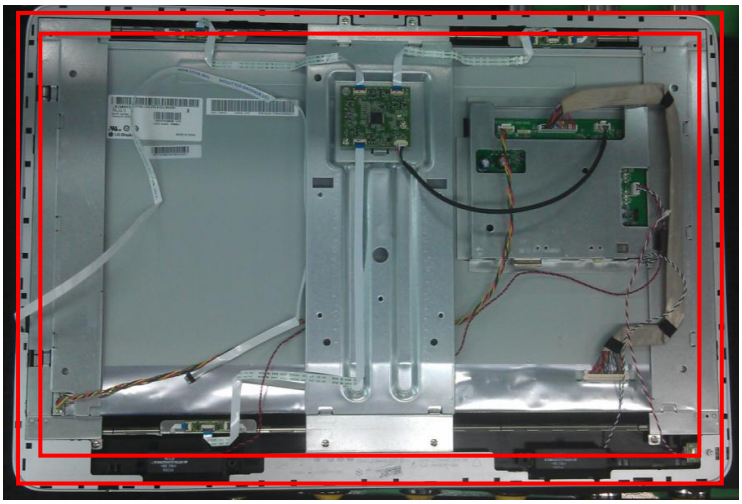
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

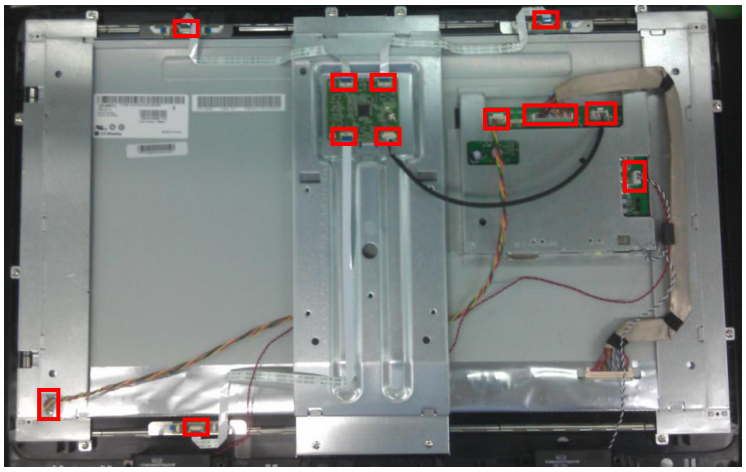
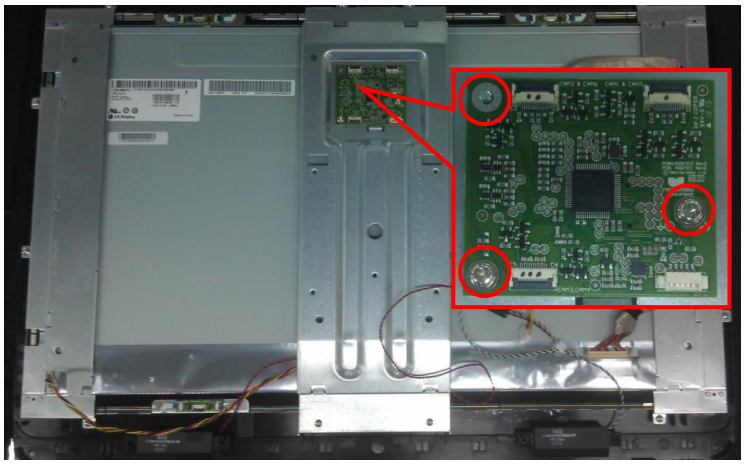
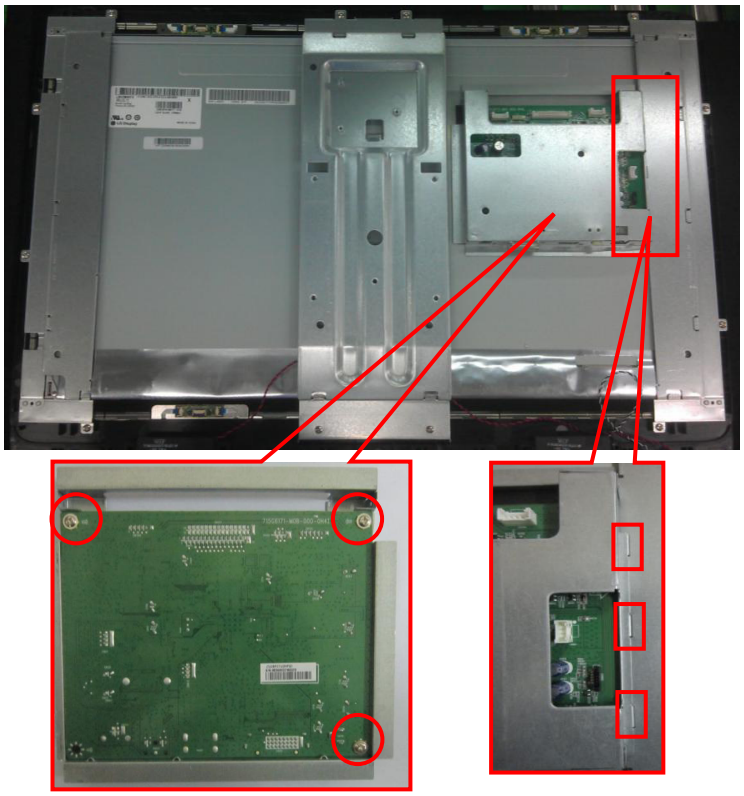
1. Take stand to backward，dismantle the screws of stand，get down the stand
2. Dismantle the cover of monitor
3. Pull out the pin of audio board，dismantle the middle frame，then dismantle the KEPC board
4. Dismantle the screw of audio board, get down the audio board
5. Pull out the pin of touch control board, dismantle the screws , get down the control board
6. Dismantle the screws of VESA_BKT to bezel，get down VESA_BKT
7. Dismantle the screws of Panel_BKT (L&R) to bezel,take out the audio,then dismantle the bezel
8. Pull out all the pin which connect main board ,get down the main shield
9. Pull out the PIN of lamp,dismantle the screws of Panel,separate the Panel_BKT(L&R)
10. Dismantle the DVI screws
11. Dismantle the Main board screws,take off mian board

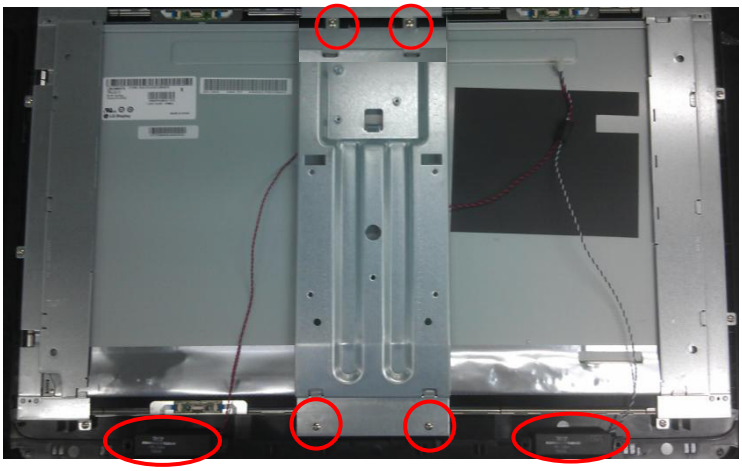
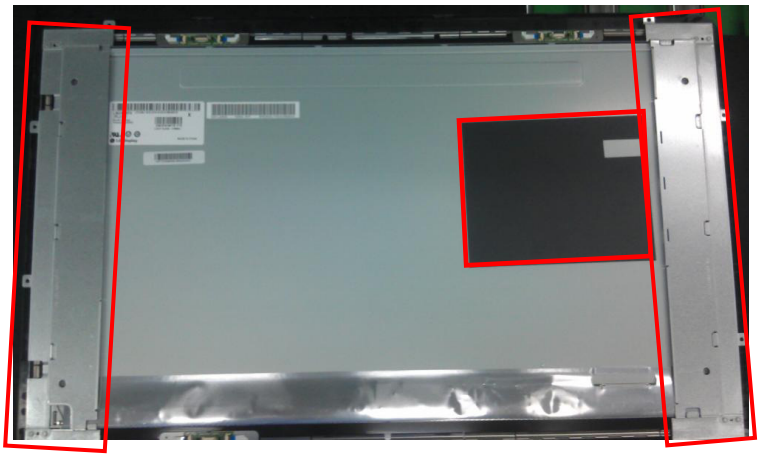
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

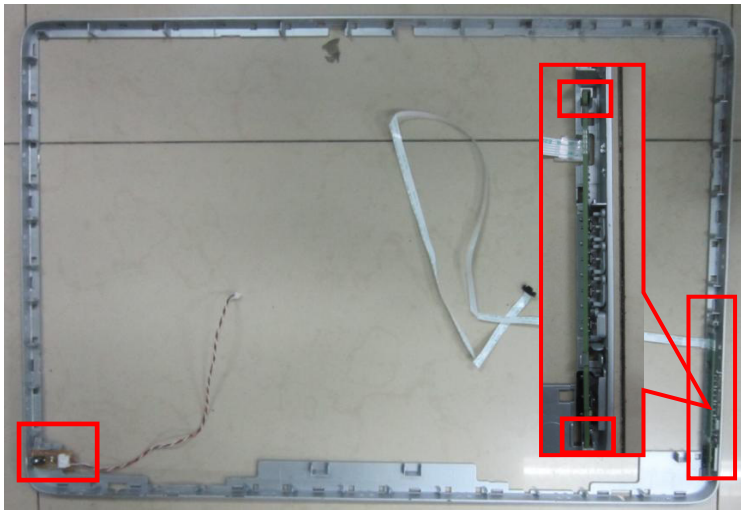
11. Mechanical Instructions

Step	Figure	Description
Preparation		Lay the monitor on a flat, soft and clean surface.
Remove the stand		Remove the screws in red to remove the stand.
Prize up the clasp to remove the Rear_Cover		Prize up the clasp to remove the Rear_Cover

Remove the screws		Remove the screws.
Remove the aluminum foil		Remove the aluminum foil.
Remove the middle frame		Remove the middle frame.

Remove the Pins		Remove the Pins.
Remove the Touch board		Remove the screws in red to remove the touch board.
Remove the Main Board		Remove the main board

Remove the BKT and Speakers		Remove the BKT and Speakers
Remove the screws	  	Remove the screws
Remove the BKT and MYLAR		Remove the BKT and mylar

Panel		Panel
Remove the speaker net		Remove the speaker net
Remove the Key Board and Audio Board		Remove the key board and audio board